



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant(s)	Wang	Examiner:	Warren, Matthew E.
Serial No.:	10/736,486	Group Art Unit:	2815
Confirmation No.:	1290	Docket:	669-77 CON/CIP
Filed:	December 15, 2003	Dated:	March 23, 2005
For:	HIGH DENSITY INTEGRATED CIRCUITS AND THE METHOD OF PACKAGING THE SAME		

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

*I hereby certify this correspondence is being deposited with the United States Postal Service as first class mail, postpaid in an envelope, addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, Virginia 22313-1450 On: March 23, 2005*

By: M.J. Mullin  
M.J. Mullin

## TRANSMITTAL OF FORMAL DRAWINGS

Siri:

Attached please find five (5) sheets of formal drawings for the above-referenced application.

Respectfully submitted,

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